



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260806004.1	PCN Issued	August 07, 2026
Qualification of RFAB as an additional Fab site option, Die Revision, Datasheet, BOM update and MLA, CDAT, FMX as an additional Assembly site options for select devices		Sample request deadline:	October 06, 2026
		Estimated 1st ship date:	November 05, 2026
Sample requests received after October 06, 2026 will not be supported.			

Change type(s)

Assembly Site
Assembly Material
Packing/Shipping/Labeling
Design
Data Sheet/Electrical Specification
Wafer Fab Site
Wafer Fab Material
Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option, BOM update & MLA, CDAT, FMX as additional Assembly site options for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter
FFAB	ASLNONC10	200mm	RFAB	LBC9	300mm

The die was also changed as a result of the process change.

Construction differences are as follows:

Group 1 device

	Current BOM	Additional BOM
Wire bond diam/type	0.96mil Cu	0.8mil Cu

*Remain on current assembly site

Group 2 device

	Current Site	Additional Site
Assembly/Test site	FMX	MLA
Wire bond diam/type	0.96mil Cu	0.8mil Cu

Group 3 device

	Current Site	Additional Site
Assembly/Test site	MLA	CDAT
Wire bond type/diam	0.96mil Cu	0.8mil Cu
Mount compound	4205846	4207123
Mold compound	4208625	4222198
Lead finish	NiPdAu	Matte Sn

Group 4 device

	Current Site	Additional Site
Assembly/Test site	MLA	FMX
Wire bond type/diam	0.96mil Cu	0.8mil Cu

Data sheet update

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.



SN74CBTLV3125

SCDS037K – DECEMBER 1997 – REVISED JULY 2026

Changes from Revision J (October 2003) to Revision K (July 2026)

Page

• Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section.....	1
• Added Applications section.....	1
• Added packages with 125°C capability.....	1
• Added specifications for DYY and BQB packages.....	4
• Updated thermal information for all packages.....	4
• Added Typical Characteristics.....	6



SN74CBTLV3126

SCDS038N – DECEMBER 1997 – REVISED JULY 2026

Changes from Revision M (January 2026) to Revision N (July 2026)

Page

• Added packages with 125°C capability.....	1
• Added specifications for DYY and BQB packages.....	5
• Updated thermal information for all packages.....	6
• Added Typical Characteristics.....	8

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
SN74CBTLV3125	SCDS037J	SCDS037K	http://www.ti.com/product/SN74CBTLV3125
SN74CBTLV3126	SCDS038M	SCDS038N	http://www.ti.com/product/SN74CBTLV3126

Qual details are provided in the Qual Data Section. Test coverage, insertions, conditions will remain consistent with current testing.

Reason for Change:	Supply Continuity
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Anticipated impact on Form, Fit, Function, Quality or Reliability:	These devices include new die based on existing schematics in a larger diameter wafer fab with a die shrink. There are changes in the electrical tables. Physical aspects of the device have changed. Review updated datasheets and/or request the Supporting Data Packet (SDP) for more details on the changes. Evaluating samples is encouraged.																																
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. <table border="1"> <thead> <tr> <th>RoHS</th> <th>REACH</th> <th>Green Status</th> <th>IEC 62474</th> </tr> </thead> <tbody> <tr> <td>☒ No Change</td> <td>☒ No Change</td> <td>☒ No Change</td> <td>☒ No Change</td> </tr> </tbody> </table>	RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change																								
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☒ No Change	☒ No Change	☒ No Change	☒ No Change																														
Changes to product identification resulting from this PCN:	Fab Site Information <table border="1"> <thead> <tr> <th>Chip Site</th> <th>Chip Site Origin Code (20L)</th> <th>Chip Site Country Code (21L)</th> <th>Chip Site City</th> </tr> </thead> <tbody> <tr> <td>FFAB</td> <td>TID</td> <td>DEU</td> <td>Freising</td> </tr> <tr> <td>RFAB</td> <td>RFB</td> <td>USA</td> <td>Richardson</td> </tr> </tbody> </table> Die Rev: Current New <table border="1"> <tbody> <tr> <td>Die Rev [2P]</td> <td>Die Rev [2P]</td> </tr> <tr> <td>C</td> <td>A</td> </tr> </tbody> </table> Assembly Site Information <table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin (22L)</th> <th>Assembly Country Code (23L)</th> <th>Assembly City</th> </tr> </thead> <tbody> <tr> <td>FMX</td> <td>MEX</td> <td>MEX</td> <td>Aguascalientes</td> </tr> <tr> <td>CDAT</td> <td>CDA</td> <td>CHN</td> <td>Chengdu</td> </tr> <tr> <td>MLA</td> <td>MLA</td> <td>MYS</td> <td>Kuala Lumpur</td> </tr> </tbody> </table> Sample product shipping label (not actual product label): 	Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City	FFAB	TID	DEU	Freising	RFAB	RFB	USA	Richardson	Die Rev [2P]	Die Rev [2P]	C	A	Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City	FMX	MEX	MEX	Aguascalientes	CDAT	CDA	CHN	Chengdu	MLA	MLA	MYS	Kuala Lumpur
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MLA	MLA	MYS	Kuala Lumpur																														

Group 1 Products Affected:			
SN74CBTLV3125PWR	SN74CBTLV3126PWR	SN74CBTLV3126PWRG	4
Group 2 Products Affected:			

74CBTLV3126DBQRG4	SN74CBTLV3125DBQ R	SN74CBTLV3126DBQ R	
Group 3 Products Affected:			
74CBTLV3125RGYRG4	SN74CBTLV3125RGYR	SN74CBTLV3126RGYR	
Group 4 Products Affected:			
SN74CBTLV3125DR	SN74CBTLV3125DRG4	SN74CBTLV3126DR	

Group 1 Qualification Report

Approve Date 29-August-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CBTLV3126PWR	QBS Reference: BQ79600PWRQ1	QBS Reference: SN74AC165PWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74CBTLV3126PWR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2503-088

Qualification Report

Approve Date 21-November-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CBTLV3125PWR	QBS Reference: BQ79600PWRQ1	QBS Reference: SN74AC165PWRQ1	QBS Reference: SN74CBTLV3126PWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	1/45/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74CBTLV3125PWR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2508-083

Group 2 Qualification Report

Approve Date 14-July-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CBTLV3125DBQR	Qual Device: SN74CBTLV3126DBQR	QBS Reference: SN74HCST74QPWRQ1	QBS Reference: SN74LVC8T245DBR	QBS Reference: 74ACT16374DLR	QBS Reference: GD75232DBR	QBS Reference: SN74CB3T3245DBQR	QBS Reference: SN74CBTLV3126PWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	-	1/77/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	1/77/0	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	1/77/0	1/77/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	1/77/0	3/231/0	1/77/0	1/77/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	1/77/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	1/77/0	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	-	-	-	-

SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-	-	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	1/3/0	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0	-	-	-	-	1/30/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74CBTLV3125DBQR is qualified at MSL2 260C

Qual Device SN74CBTLV3126DBQR is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2410-087

Group 3 Qualification Report

Approve Date 19-December-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CBTLV3125RGYR	Qual Device: SN74CBTLV3126RGYR	QBS Reference: TLV62568DBVR	QBS Reference: XM0C1104QRUKRQ1	QBS Reference: CAHCT1G125WDTXRQ1	QBS Reference: SN74CBTLV3126PWR	QBS Reference: SN74CBTLV3125PWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	1/77/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	1/77/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	1/77/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0	1/45/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	1/77/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/3000/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0	1/10/0	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	1/3/0	-	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	1/3/0	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	1/3/0	-	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	-	1/30/0	-	-	-	1/30/0	1/30/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74CBTLV3125RGYR is qualified at MSL2 260C

Qual Device SN74CBTLV3126RGYR is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2506-058

Group 4 Qualification Report

Approve Date 15-December-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CBTLV3125DR	Qual Device: SN74CBTLV3126DR	QBS Reference: SN74HCST4QPWRQ1	QBS Reference: TLC3555QDRQ1	QBS Reference: LP2951-50QDRQ1M3	QBS Reference: SN74LVC165ADRQ1	QBS Reference: SN74CBTLV3126PWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-	1/77/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	1/77/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	1/45/0	1/45/0	1/45/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	1/10/0	1/10/0	1/10/0	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	1/3/0	-	-	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	1/3/0	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	1/3/0	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0	1/3/0	1/3/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0	-	-	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0	3/90/0	1/30/0	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74CBTLV3125DR is qualified at MSL1 260C

Qual Device SN74CBTLV3126DR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2506-057

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic

data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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